

RDA M-8AN Flip Chip Aligner Bonder

DESCRIPTION:

Microprocessor-controlled visible optics system that permits rapid, repeatable alignment and bonding of a flipped die to a substrate.

- Accommodates a variety of contact pads
- Programmable combinations of pressure, substrate heating and die heating (optional)
- Six axis alignment
- Auto collimator (visible)
- In-line contact force indicator
- Temperature-controlled lower / upper chucks
- Custom chucks to hold various samples
- Motorized X-Y camera scanning and focusing
- Non-contact optical leveling range: 3°
- X-Y Dynamic Range: 25 mm
- Theta Dynamic Force: -50 lb



LOCATION: PROCESS DESIGN AND ANALYSIS LABORATORY, ROOM B7

[CONTACT US](#)

CONTACTS

For more information or to arrange for the use of this equipment, contact any of the IEEC staff members listed below:

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